Board Characteristics
0. All dimensions are given in inches unless specified otherwise.

5. Immersion Gold over copper, with min. Ni: 3-7 um; Au: 0.05-0.12 um.
   Apply Solder Mask over bare copper.
10. FMS tolerances: +/- 0.003 unless specified otherwise.

12. This is a pressfit technology thru hole with the following specs:
   12-1. Finished plated hole size: 1.00 - 1.10 mm.
   12-2. Drilled hole size: 1.10mm +/- 0.02mm.
   12-3. Min. Thickness of thru hole plating: Cu: 25 um; Ni: 3-7 um; Au: 0.05-0.12 um.

BOARD'S DRILL SCHEDULE

<table>
<thead>
<tr>
<th>DRILL SYMBOL</th>
<th>DRILL SIZE</th>
<th>COUNT</th>
<th>PLATED</th>
<th>TOLERANCE</th>
<th>COMMENT</th>
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<tr>
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<td>Note 12.</td>
<td>Note 12</td>
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<td>H</td>
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<td>84</td>
<td>NO</td>
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UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

QUIET - EB Backplane -P2
Specification Drawing

A - 2600
A